



BSI Standards Publication

Semiconductor devices — mechanical and climatic test methods

Part 42: Temperature humidity storage

bsi.

...making excellence a habit.TM

National foreword

This British Standard is the UK implementation of EN 60749-42:2014. It is identical to IEC 60749-42:2014.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its secretary.

This publication does not purport to include all the necessary provisions of a contract. Users are responsible for its correct application.

© The British Standards Institution 2014.
Published by BSI Standards Limited 2014

ISBN 978 0 580 79091 1
ICS 31.080.01

Compliance with a British Standard cannot confer immunity from legal obligations.

This British Standard was published under the authority of the Standards Policy and Strategy Committee on 31 October 2014.

Amendments/corrigenda issued since publication

Date	Text affected

EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN 60749-42

October 2014

ICS 31.080.01

English Version

**Semiconductor devices - Mechanical and climatic test methods -
Part 42: Temperature and humidity storage
(IEC 60749-42:2014)**

Dispositifs à semiconducteurs - Méthodes d'essais
mécaniques et climatiques - Partie 42: Stockage de
température et d'humidité
(CEI 60749-42:2014)

Halbleiterbauelemente - Mechanische und klimatische
Prüfverfahren - Teil 42: Lagerung bei Wärme und Feuchte
(IEC 60749-42:2014)

This European Standard was approved by CENELEC on 2014-09-16. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Croatia, Cyprus, the Czech Republic, Denmark, Estonia, Finland, Former Yugoslav Republic of Macedonia, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Romania, Slovakia, Slovenia, Spain, Sweden, Switzerland, Turkey and the United Kingdom.



European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

Foreword

The text of document 47/2200/FDIS, future edition 1 of IEC 60749-42, prepared by IEC/TC 47 "Semiconductor devices." was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 60749-42:2014.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2015-06-16
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2017-09-16

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CENELEC [and/or CEN] shall not be held responsible for identifying any or all such patent rights.

Endorsement notice

The text of the International Standard IEC 60749-42:2014 was approved by CENELEC as a European Standard without any modification.

Annex ZA
(normative)**Normative references to international publications
with their corresponding European publications**

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60749-20	-	Semiconductor devices - Mechanical and climatic test methods -- Part 20: Resistance of plastic encapsulated SMDs to the combined effect of moisture and soldering heat	EN 60749-20	-

CONTENTS

1	Scope	5
2	Normative references	5
3	Test equipment.....	5
3.1	Capacity of the equipment	5
3.2	Materials and construction of the thermostatic/humidistatic chamber	5
3.3	Water to be used in the test	5
4	Procedure.....	5
4.1	Preconditioning	5
4.2	Initial measurements.....	6
4.3	Tests	6
4.3.1	Inserting and removing specimens.....	6
4.3.2	Test conditions	6
4.3.3	Test duration	6
4.3.4	Post treatment.....	7
4.3.5	End-point measurement.....	7
5	Failure criteria	7
6	Information to be given in applicable procurement document.....	8
	Figure 1 – Unsaturated pressurized vapour test conditions profile.....	7
	Table 1 – Temperature and humidity storage test conditions	6

SEMICONDUCTOR DEVICES – MECHANICAL AND CLIMATIC TEST METHODS –

Part 42: Temperature and humidity storage

1 Scope

This part of IEC 60749 provides a test method to evaluate the endurance of semiconductor devices used in high temperature and high humidity environments.

This test method is used to evaluate the endurance against corrosion of the metallic interconnection of chips of semiconductor devices contained in plastic moulded and other types of packages. It is also used as a means of accelerating the leakage phenomena due to the moisture penetration through the passivation film and as a pre-conditioning for various kinds of tests.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60749-20, *Semiconductor devices – Mechanical and climatic test methods – Part 20: Resistance of plastic encapsulated SMDs to the combined effect of moisture and soldering heat*

3 Test equipment

3.1 Capacity of the equipment

The chamber to be used in this test shall be capable of maintaining the test temperature and humidity conditions specified in 4.3 throughout the test duration.

3.2 Materials and construction of the thermostatic/humidistatic chamber

The chamber shall be made of materials that do not deteriorate under high humidity conditions. The design of the chamber shall prevent water condensed on the ceiling of the chamber from dropping on the specimen.

3.3 Water to be used in the test

Water to be used in the tests shall be distilled water or deionised water, with a resistivity of 500 Ωm or more at 23 °C.

4 Procedure

4.1 Preconditioning

When the specimen is a plastic-moulded SMD, the moisture soaking and soldering heat stress treatment specified in IEC 60749-20 shall be carried out before executing this test.

4.2 Initial measurements

The initial measurements shall be carried out in accordance with the applicable procurement document.

4.3 Tests

4.3.1 Inserting and removing specimens

The specimens shall be placed in the chamber at the high temperature and high humidity conditions required by the applicable procurement document. When putting the specimen in and out of the chamber, care shall be taken to ensure that water droplets not to adhere to the specimen and that the specimen does not come into contact with any condensed water.

NOTE When a SMD is to be mounted on a jig for evaluation, the relevant conditions (board materials, size of the land, soldering method, flux cleaning, etc.) are specified in the applicable procurement document.

4.3.2 Test conditions

The temperature and humidity conditions shall be selected from Table 1. Unless otherwise required by the applicable procurement document, condition C shall be used. Where Conditions D, E, and F are specified, the temperature shall be controlled from the start to the end of the test and the humidity shall be controlled between temperature ramp-up and temperature ramp-down, in accordance with the profile of Figure 1, unless otherwise specified in the applicable procurement document. Care should be taken because failure modes consisting of short-circuits (leaks) between external leads through plating metal, that do not occur in the field, may occur under condition C (temperature 85 °C, humidity 85 %), and conditions D, E, and F (the unsaturated pressurized vapour test).

4.3.3 Test duration

The test duration shall be in accordance with Table 1, except when otherwise specified in the applicable procurement document. In this case, acceleration and diffusion models that estimate moisture exposure duration in the use conditions shall be documented and added to the procurement document. Under conditions D, E, and F, the time count shall be started when the vapour pressure and temperature stabilise as shown in Figure 1.

Table 1 – Temperature and humidity storage test conditions

Test condition	Temperature °C	Humidity %	Test duration h	Vapor pressure ^a Pa
A	40 ± 2	90 ± 5	8 000 ⁺¹⁶⁸ ₋₂₄	7,4 × 10 ³
B	60 ± 2	90 ± 5	4 000 ⁺¹⁶⁸ ₋₂₄	1,9 × 10 ⁴
C	85 ± 2	85 ± 5	1 000 ⁺¹⁶⁸ ₋₂₄	5,0 × 10 ⁴
D	110 ± 2	85 ± 5	264 ⁺⁸ ₀	1,2 × 10 ⁵
E	120 ± 2	85 ± 5	168 ⁺⁴ ₀	1,7 × 10 ⁵
F	130 ± 2	85 ± 5	96 ⁺² ₀	2,3 × 10 ⁵
^a Reference value				

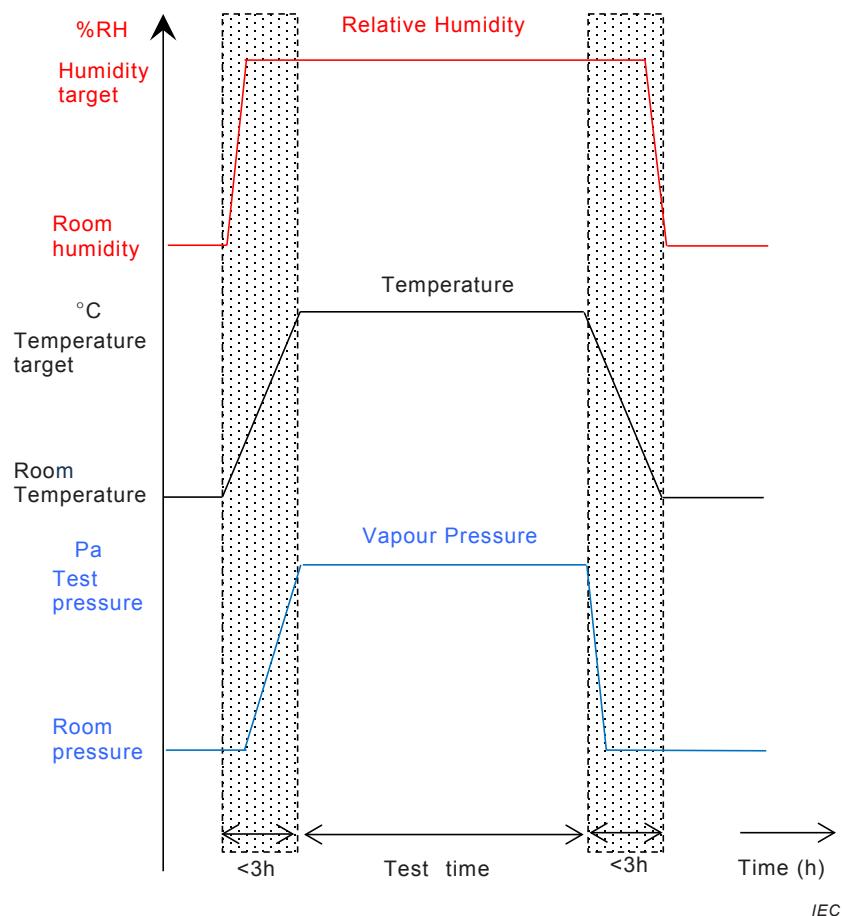


Figure 1 – Unsaturated pressurized vapour test conditions profile

4.3.4 Post treatment

After completion of the test and confirmation that the interior of the chamber has returned approximately to the specified temperature and humidity profile, the specimen shall be removed from the chamber and left at room temperature. The specimens shall be maintained at room ambient, for between 2 h and the completion of the electrical test.

Under conditions D, E, and F, special care shall be taken when handling the specimen after finishing the test, because failure modes different from those ones of the tests may occur due to condensation, sudden changes in the temperature and pressure, and other relevant factors.

4.3.5 End-point measurement

The end-point measurements shall be carried out according to the applicable procurement document.

These measurements shall be carried out within 48 h at room ambient after the completion of the tests, except when otherwise specified in the applicable procurement document.

NOTE Where completion of the end point measurement is expected to exceed 48 h, the moisture loss can be reduced by placing the device in a moisture barrier bag sealed in ambient air without vacuum or desiccant within 6 h after removal from the test chamber.

5 Failure criteria

A device will be considered to have failed if parametric limits are exceeded, or if functionality cannot be demonstrated under nominal and worst-case conditions, as specified in the relevant

specification or data sheet. Electrical failures due to external package damage which are an artefact of the test method shall be excluded from the failure classification.

6 Information to be given in applicable procurement document

- a) initial measurements (see 4.2);
 - b) test condition (other than as specified) (see 4.3.2);
 - c) test duration (other than as specified) (see 4.3.3);
 - d) post treatment (other than as specified) (see 4.3.4);
 - e) end-point measurements (other than as specified) (see 4.3.5);
 - f) storage conditions (other than as specified) (see 4.3.5).
-

This page deliberately left blank

British Standards Institution (BSI)

BSI is the national body responsible for preparing British Standards and other standards-related publications, information and services.

BSI is incorporated by Royal Charter. British Standards and other standardization products are published by BSI Standards Limited.

About us

We bring together business, industry, government, consumers, innovators and others to shape their combined experience and expertise into standards-based solutions.

The knowledge embodied in our standards has been carefully assembled in a dependable format and refined through our open consultation process. Organizations of all sizes and across all sectors choose standards to help them achieve their goals.

Information on standards

We can provide you with the knowledge that your organization needs to succeed. Find out more about British Standards by visiting our website at bsigroup.com/standards or contacting our Customer Services team or Knowledge Centre.

Buying standards

You can buy and download PDF versions of BSI publications, including British and adopted European and international standards, through our website at bsigroup.com/shop, where hard copies can also be purchased.

If you need international and foreign standards from other Standards Development Organizations, hard copies can be ordered from our Customer Services team.

Subscriptions

Our range of subscription services are designed to make using standards easier for you. For further information on our subscription products go to bsigroup.com/subscriptions.

With **British Standards Online (BSOL)** you'll have instant access to over 55,000 British and adopted European and international standards from your desktop. It's available 24/7 and is refreshed daily so you'll always be up to date.

You can keep in touch with standards developments and receive substantial discounts on the purchase price of standards, both in single copy and subscription format, by becoming a **BSI Subscribing Member**.

PLUS is an updating service exclusive to BSI Subscribing Members. You will automatically receive the latest hard copy of your standards when they're revised or replaced.

To find out more about becoming a BSI Subscribing Member and the benefits of membership, please visit bsigroup.com/shop.

With a **Multi-User Network Licence (MUNL)** you are able to host standards publications on your intranet. Licences can cover as few or as many users as you wish. With updates supplied as soon as they're available, you can be sure your documentation is current. For further information, email bsmusales@bsigroup.com.

BSI Group Headquarters

389 Chiswick High Road London W4 4AL UK

Rewvisions

Our British Standards and other publications are updated by amendment or revision. We continually improve the quality of our products and services to benefit your business. If you find an inaccuracy or ambiguity within a British Standard or other BSI publication please inform the Knowledge Centre.

Copyright

All the data, software and documentation set out in all British Standards and other BSI publications are the property of and copyrighted by BSI, or some person or entity that owns copyright in the information used (such as the international standardization bodies) and has formally licensed such information to BSI for commercial publication and use. Except as permitted under the Copyright, Designs and Patents Act 1988 no extract may be reproduced, stored in a retrieval system or transmitted in any form or by any means – electronic, photocopying, recording or otherwise – without prior written permission from BSI. Details and advice can be obtained from the Copyright & Licensing Department.

Useful Contacts:

Customer Services

Tel: +44 845 086 9001

Email (orders): orders@bsigroup.com

Email (enquiries): cservices@bsigroup.com

Subscriptions

Tel: +44 845 086 9001

Email: subscriptions@bsigroup.com

Knowledge Centre

Tel: +44 20 8996 7004

Email: knowledgecentre@bsigroup.com

Copyright & Licensing

Tel: +44 20 8996 7070

Email: copyright@bsigroup.com



...making excellence a habit.TM